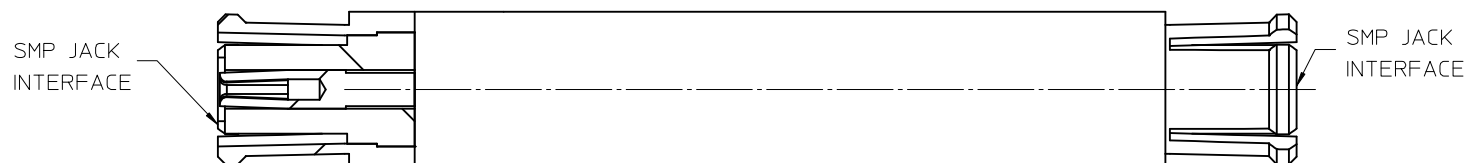
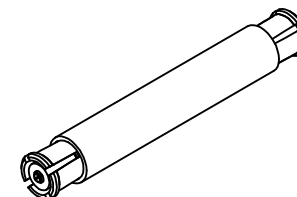


MATERIALS AND FINISHES:

BODY BERYLLIUM COPPER
PLATED GOLD

CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON



DETAIL DRAWING - SEE 73415-335 .

73406-0115	PLACE 73415-3359 INTO SMALL TRAY
73406-0114	PLACE 73415-3358 INTO SMALL TRAY
73406-0113	PLACE 73415-3357 INTO SMALL TRAY
73406-0112	PLACE 73415-3354 INTO SMALL TRAY
73406-0111	PLACE 73415-3353 INTO SMALL TRAY
73406-0110	PLACE 73415-3352 INTO SMALL TRAY
PART NO.	DESCRIPTION

PS-89675-3320	PRODUCT SPECIFICATION
MIL-STD-348A, FIG. 326.1	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: NEW RELEASE
EC NO: URF2009-0353
DRW: CLLI 2009/01/05
CHKD: 2009/01/06
APPR: MHUANG 2009/01/06

QUALITY SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± .005	± .0004
3 PLACES	± .005	± .0004
2 PLACES	± .005	± .0004
1 PLACE	± .005	± .0004

ANGULAR ± 2 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM/IN

DRAWN BY	DATE
CLLI	2008/12/24
CHECKED BY	DATE
KERRIE	2008/12/24
APPROVED BY	DATE
MISEN	2008/12/24

MATERIAL NO.
SEE TABLE

SIZE
C

SCALE
DESIGN UNITS
METRIC

THIRD ANGLE PROJECTION

TITLE
SMP JACK TO JACK ADAPTER
50 OHMS SMP-J/J/ADP

MOLEX INCORPORATED

DOCUMENT NO.
SD-73406-011

SHEET NO.
1 OF 1

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